#### 505604729 08/04/2019

### PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5651530

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
Kun-Ju Li	07/30/2019
Tai-Cheng Hou	07/30/2019
Hsin-Jung Liu	07/30/2019
Fu-Yu Tsai	07/30/2019
Bin-Siang Tsai	07/30/2019
Chau-Chung Hou	07/30/2019
Yu-Lung Shih	07/30/2019
Ang Chan	07/30/2019
Chih-Yueh Li	07/30/2019
Chun-Tsen Lu	07/30/2019

### **RECEIVING PARTY DATA**

Name:	UNITED MICROELECTRONICS CORP.	
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park	
City:	Hsin-Chu City	
State/Country:	TAIWAN	

### **PROPERTY NUMBERS Total: 1**

Property Type	Number	
Application Number:	16531108	

### **CORRESPONDENCE DATA**

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Email: Patent.admin.uspto.cr@naipo.com

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Address Line 4: NEW TAIPEI CITY, TAIWAN

ATTORNEY DOCKET NUMBER: NAUP3468USA NAME OF SUBMITTER: SIBYL YU

SIGNATURE:	/SIBYL YU/
DATE SIGNED:	08/04/2019
Total Attachments: 20	
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# Title of Invention: SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

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☑ The attached application, or			
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representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WITNESS WHEREOF, I have he	plication, said invention and said lecessary or desirable to carry out	Letters Patent and sa the proposes thereo	of.
Note: An application data sheet (PTG	O/SB/14 or equivalent), including	naming the entire	

Page 1 of 20

inventive entity, must accompany this form. Use this form for each additional inventor.

NPO#NAU-P3468-USA:0 CUST#UMCD-2019-0235

LEGAL NAME OF INVENTOR(ASSIGNOR)					
Inventor:	Kun-Ju Li	Date:	JUL 3 0 2019		
Signature:	Kun-Ju Li				

NPO#NAU-P3468-USA:0 CUST#UMCD-2019-0235 Page 2 of 20

F#NPO-P0002E-US1201 DSB0-108U015375

## Title of Invention: SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

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NPO#NAU-P3468-USA:0 CUST#UMCD-2019-0235

LEGAL NAME OF INVENTOR(ASSIGNOR)					
Inventor:	Tai-Cheng Hou	Date:	JUL 3 0 2019		
Signature:	Tai-Cheng Hou			_	

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Page

F#NPO-P0002E-US1201 DSB0-108U015375

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I hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement or encumbran n this assignment;	ice has	been or will be made	or
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representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WITNESS WHEREOF, I have her	olication, said invention and said Lecessary or desirable to carry out	etters F	Patent and said poses thereof.	
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Page 5 of 20

NPO#NAU-P3468-USA:0 CUST#UMCD-2019-0235

LEGAL NAME OF INVENTOR(ASSIGNOR)					
Inventor:	Hsin-Jung Liu	Date:	JUL 3 0 2019		
Signature:	Hsin-Jung Liu			-	

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NPO#NAU-P3468-USA:0 CUST#UMCD-2019-0235

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representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WITNESS WHEREOF, I have he	olication, said invention an ecessary or desirable to ca	d said Letters Parry out the prop	atent and said ooses thereof.	
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NPO#NAU-P3468-USA:0 CUST#UMCD-2019-0235

LEGAL NAME OF INVENTOR(ASSIGNOR)					
Inventor:	Fu-Yu Tsai	Date:	JUL 3 0 2019	_	
Signature:	Fu-Yu Tsai			_	

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F#NPO-P0002E-US1201 DSB0-108U015375

NPO#NAU-P3468-USA:0 CUST#UMCD-2019-0235

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Page 9 of 20

LEGAL NAI	WE OF INVENTOR(ASSIGNOR)		
Inventor:	Bin-Siang Tsai	Date:	JUL 3 0 2019
Signature:	Bon · Siang 7500		

Page 10 of 20

F#NPO-P0002E-US1201 DSB0-108U015375

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I hereby covenant that no assignment, sale, agreentered into which would conflict with this assign	ement or encumbrance has t ment;	peen or will be made or
I further covenant that ASSIGNEE will, upon its r and documents relating to said invention and sai known and accessible to I and will testify as to th related thereto and will promptly execute and del	d Letters Patent and legal eque same in any interference, li	uivalents as may be tigation proceeding
representatives any and all papers, instruments of maintain, issue and enforce said application, said equivalents thereof which may be necessary or of IN WITNESS WHEREOF, I have hereunto set has	d invention and said Letters P desirable to carry out the prop	atent and said
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Page 11 of 20

NPO#NAU-P3468-USA:0 CUST#UMCD-2019-0235

LEGAL NAI	ME OF INVENTOR(ASSIGNOR)			
Inventor:	Chau-Chung Hou	Date:	JUL 3 0 2019	
Signature:	Chau-Chung Hou			

Page 12 of 20

NPO#NAU-P3468-USA:0 CUST#UMCD-2019-0235

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NPO#NAU-P3468-USA:0 CUST#UMCD-2019-0235

				Docket No NAUP3	400USA
LEGAL NA	ME OF INVENT	OR(ASSIGNOR)			
Inventor:	Yu-Lung Sh		Date:	JUL 3 0 2019	
Signature:	Yu-Lung	Shih			-
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LEGAL NA	ME OF INVENTO	R(ASSIGNOR)				
Inventor:	Ang Chan		Date:	JUL	3 0 2019	
Signature:	Ang	Chan				-
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LEGAL NAI	ME OF INVENTOR(ASSIGNOR)		
Inventor:	Chih-Yueh Li	Date:	JUL 3 0 2019
- Signature:	Chih-Yueh Li		

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LEGAL NAME OF INVENTOR(ASSIGNOR)			
Inventor:	Chun-Tsen Lu	Date:	JUL 3 0 2019
Signature:	Christen Lu	•	

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PATENT REEL: 049952 FRAME: 0442

**RECORDED: 08/04/2019**